

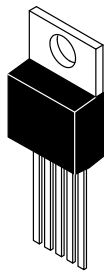
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

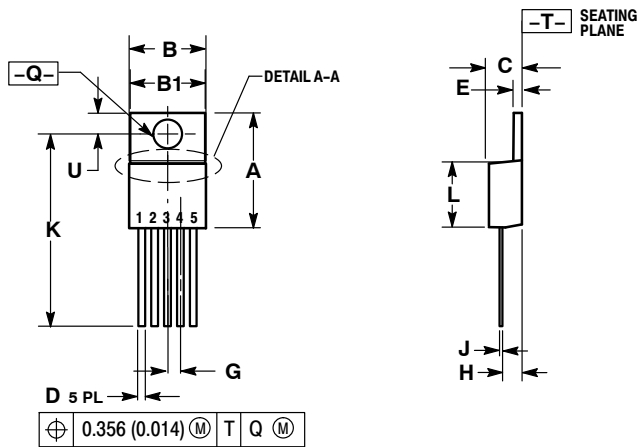


## TO-220 5-LEAD CASE 314D-04 ISSUE H

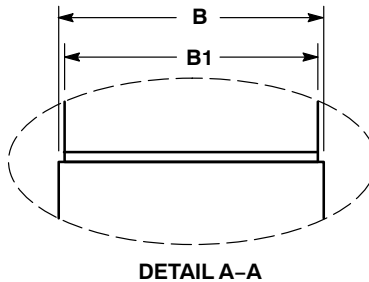
DATE 29 JAN 2010



SCALE 1:1



$\oplus$	0.356 (0.014)	M	T	Q	M
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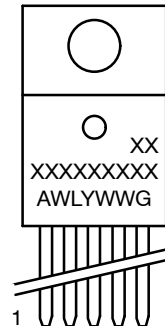
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
B1	0.375	0.415	9.525	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	0.977	1.045	24.810	26.543
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972

STYLE 1 THRU 4:  
1. OBSOLETE

### GENERIC MARKING DIAGRAM\*




- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO-220 5-LEAD	PAGE 1 OF 2



ISSUE	REVISION	DATE
F	ADDED DIMENSION B1 AND FIXED DIMENSION K. REQ. BY A. GARLINGTON.	18 AUG 2005
G	CHANGES RELATED TO CARSEM TO SEREMBAN TRANSFER. REDREW TO JEDEC STANDARDS. ADDED MARKING DIAGRAM. REQ. BY B. FONTES.	15 SEP 2009
H	DRAWING REVERTED BACK TO REVISION F FORMAT. REVISION G CHANGES WERE UNNECESSARY. REQ. BY B. FONTES.	29 JAN 2010

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